



## Features

- Very small size of 0805
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly

**Coming Soon**



**LP-ISM** series

Surface-mount devices

## Product Dimensions(mm) & Marking System

Part number	A Max	B Max	C Max	D Min	E Min	Part marking
LP-ISM010	2.20	1.50	1.00	0.10	0.20	
LP-ISM020	2.20	1.50	1.00	0.10	0.20	
LP-ISM035	2.20	1.50	0.75	0.10	0.20	
LP-ISM050	2.20	1.50	1.25	0.10	0.20	



Top View

Side View

## Electrical Characteristics

Part number	$I_H$ (A)	$I_T$ (A)	$V_{max}$ (V)	$I_{max}$ (A)	$T_{trip}$		$Pd_{typ}$ (W)	$R_{min}$ ( $\Omega$ )	$R_{1max}$ ( $\Omega$ )
					Current(A)	Time(S)			
LP-ISM010	0.10	0.30	15.0	40.0	0.50	1.50	0.5	1.00	6.00
LP-ISM020	0.20	0.50	9.00	40.0	8.00	0.02	0.5	0.65	3.50
LP-ISM035	0.35	0.75	6.00	40.0	8.00	0.10	0.5	0.25	1.20
LP-ISM050	0.50	1.00	6.00	40.0	8.00	0.10	0.5	0.15	0.85

$I_H$ =Hold current: maximum current at which the device will not trip at 25 °C still air.

$I_T$ =Trip current: minimum current at which the device will always trip at 25 °C still air.

$V_{max}$ =Maximum voltage device can withstand without damage at rated current.

$I_{max}$ =Maximum fault current device can withstand without damage at rated voltage.

$T_{trip}$ =Maximum time to trip(s) at assigned current.

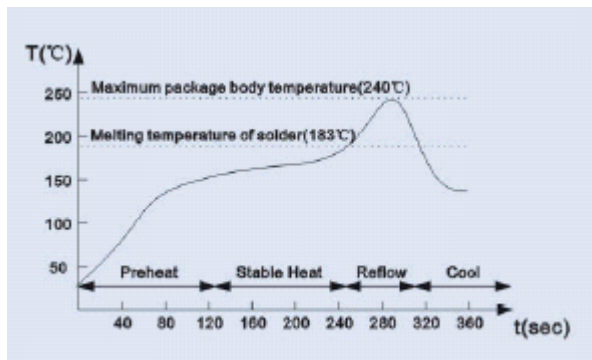
$R_{min}$ =Minimum device resistance at 25 °C prior to tripping.

$R_{1max}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

## Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25	$R_{min}$ R $R_{max}$
Time to Trip	Specified current, $V_{max}$ , 25	T maximum Time to Trip
Hold Current	30min, at $I_H$	No trip
Trip Cycle Life	$V_{max}$ , $I_{max}$ , 100cycles	No arcing or burning
Trip Endurance	$V_{max}$ , 24hours	No arcing or burning

## Solder Reflow Recommendations



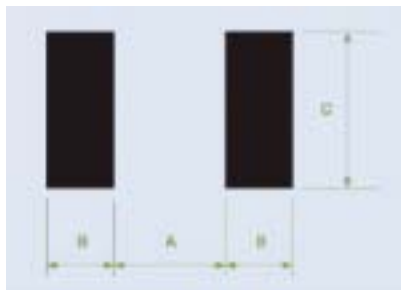
\* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

\* Devices can be cleaned using standard industry methods and solvents.

### Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Pad Dimensions



Part number	A (mm)	B (mm)	C (mm)
LP-ISM010	1.20	1.00	1.50
LP-ISM020	1.20	1.00	1.50
LP-ISM035	1.20	1.00	1.50
LP-ISM050	1.20	1.00	1.50